

L Number	Hits	Search Text	DB	Time stamp
1	93	257/777,723-725,676,684.ccls. and substrate with (through adj hole) and stack\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/10 13:18
2	2	("5994166").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/10 13:18
-	100	degani-yinon.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/09 16:32
-	42	dudderar-thomas-dixon.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/09 16:33
-	1	sun-liguo.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/09 16:34
-	3	zhao-meng.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/09 16:34
-	206	257/777,723-725,676,684.ccls. and (IC chip die) and substrate with (through adj hole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/10 13:05
-	197	257/778,685-686.ccls. and (IC chip die) and substrate with (through adj hole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/09 16:50
-	14	257/659.ccls. and (IC chip die) and substrate with (through adj hole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/09 16:51
-	123	257/737-738.ccls. and (IC chip die) and substrate with (through adj hole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/09 16:52